

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Mika KIRITANI)
Serial No.: Not yet assigned) Group Art Unit:
Filed: June 25, 2001) Examiner:

jc973 U.S. PTO
09/887104
06/25/01


For: SEMICONDUCTOR RESIN MOLD AND SEMICONDUCTOR RESIN
MOLDING METHOD USING THE MOLD

**Assistant Commissioner for Patents
Washington, DC 20231**

Sir:

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. § 1.97(b)

Pursuant to 37 C.F.R. §§ 1.56 and 1.97(b), applicant brings to the
Examiner's attention the documents listed on attached Form PTO-1449. Copies
of the listed documents are attached. Applicant respectfully requests that the
Examiner consider the documents listed on attached Form PTO-1449 and indicate
that they were considered by making an appropriate notation on this form.

This Information Disclosure Statement is being filed with the above-
referenced application.

The following is a concise statement of relevance of the non-English
language documents:

1. Japanese Published Application No. 2-295140 discloses a method of sealing a semiconductor device with resin. The method disclosed in this reference *includes a* *is featured in* that a semiconductor chip is sealed with resin after being fixed in the drag of a mold by suction.

2. Japanese Published Application No. 5-55280 discloses a method of sealing a resin-sealed type semiconductor device having a heat sink mounted on the back surface of the die pad, with resin, while fixing the die pad by suction.

This submission does not represent that a search has been made or that no better art exists and does not constitute an admission that each or all of the listed documents are material or constitute "prior art." If the Examiner applies any of the documents as prior art against any claim in the application and applicant determines that the cited documents do not constitute "prior art" under United States law, applicant reserves the right to present to the office the relevant facts and law regarding the appropriate status of such documents.

Applicant further reserves the right to take appropriate action to establish the patentability of the disclosed invention over the listed documents, should one or more of the documents be applied against the claims of the present application.

If there is any fee due in connection with the filing of this Statement, please charge the fee to our Deposit Account No. 06-0916.

Respectfully submitted,

FINNEGAN, HENDERSON, FARABOW,
GARRETT & DUNNER, L.L.P.

By:


Richard V. Burgujian
Reg. No. 31,744

Dated: June 25, 2001
Enclosures
RVB/FPD/peg

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

PTO
973 U.S. 887104
JC 09/25/01

Atty. Docket No. 04329.2583		Serial No.	Not Yet Assigned			
Applicant Mika KIRITANI						
Filing Date June 25, 2001		Group				
U.S. PATENT DOCUMENTS						
Examiner Initial*	Document Number	Date	Name	Class	Sub Class	Filing Date If Appropriate
	5,147,821	9/15/92	McShane et al.			
FOREIGN PATENT DOCUMENTS						
	Document Number	Date	Country	Class	Sub Class	Translation Yes or No
	2-295140	12/6/90	Japan			No
	5-55280	3/5/93	Japan			No
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)						
Examiner		Date Considered				
<p>*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>						